

REMARKS/ARGUMENTS

Claims 2-19 are pending in this application. By this Amendment, claims 2, 3, 8, 9 and 19 are amended. Support for the claims can be found throughout the specification, including the original claims and the drawings. Withdrawal of the rejections in view of the above amendments and the following remarks is respectfully requested.

I. Rejection Under 35 U.S.C. §102(b)

The Office Action rejects claims 2-7 under 35 U.S.C. §102(b) over Hirobumi et al., Japanese Patent Publication No. 2001-110939 (hereinafter "Hirobumi"). The rejection is respectfully traversed.

Independent claim 2 is directed to a plating method for a printed circuit board. The method includes, *inter alia*, providing a substrate having a plurality of connection pads and circuit patterns connected to the connection pads, using some of the circuit patterns provided in the substrate as a first power connection portion and some of the circuit patterns as a second power connection portion, and selectively connecting the first or the second power connection portion to an external power source, covering a surface of the substrate excepting the connection pads with a plating resistance resist to shield it. The method also includes selectively supplying power to one of the first or the second power connection portion, and forming a gold-plated layer on a connection pad to which the one of the first or the second power connection portion is electrically connected, and disconnecting the one of the first or the second power connection

portion from the external power source. Hirobumi neither discloses nor suggests such features, or the claimed combination of features.

Hirobumi discloses a method of manufacturing a semiconductor package in which non-electrolytic copper is deposited on an entire surface of a substrate, a plating resist material is deposited on a solder surface, and a portion of the non-electrolytic copper is removed by etching. An electrolytic nickel/gold coat is applied to an exposed surface of a copper pad, and resist material is removed. Applicant maintains the previously established position that Hirobumi neither discloses nor suggests that any portion of the resulting circuit patterns are connected to any type of external power source to form a gold plated layer in the manner recited in independent claim 2.

The Advisory Action asserts that current flows through a conductive layer 5 on a side of a circuit board (presumably, the bottom side as shown in the drawings) opposite a bonding pad (unspecified), through a through hole 3, through a circuit pattern formed on a top side of the board, and to a bonding pad that is exposed to a plating solution through an opening in a resist material 4. Applicant maintains the previously established position that any such connection of the conductive layer 5 to an alleged external power source would not necessarily carry any externally supplied power along the suggested path. However, even if this were the case, Hirobumi still only discloses the connection to and supply of power at a single point of the conductive layer 5. Hirobumi neither discloses nor suggests first and second power connection

portions, let alone first and second power connection portions operated in the manner recited in independent claim 2.

Accordingly, it is respectfully submitted that independent claim 2 is not anticipated by Hirobumi, and thus the rejection of independent claim 2 under 35 U.S.C. §102(b) over Hirobumi should be withdrawn. Dependent claims 3-7 are allowable at least for the reasons set forth above with respect to independent claim 2, from which they depend, as well as for their added features.

II. Rejection Under 35 U.S.C. §103(a)

The Office Action rejects claims 8-19 under 35 U.S.C. §103(a) over Figures 1-3 of the present application in view Hirobumi. The rejection is respectfully traversed.

Independent claim 9 is directed to a plating method for a printed circuit board. The method includes using some of a plurality of circuit patterns provided at a surface of a substrate as first and second power connection portions and connecting the first power connection portion to an external power source, covering the surface of the substrate having a ball pad formed thereon with a plating resistance resist to shield it, supplying power to the bonding pad through the first power connection portion for forming a gold-plated layer on the bonding pad, and removing the connection from the external power source to the first power connection portion.

The method also includes connecting the second power connection portion to the external power source and coating a plating resistance resist at a surface of the substrate with the

bonding pad formed thereon to shield it, supplying power to the ball pad through the second power connection portion for forming a gold-plated layer on the ball pad, and removing the connection from the external power source to the second power connection portion. Independent claim 19 recites similar features in varying scope.

As acknowledged in the Office Action, Figures 1-3 of the present application neither disclose nor suggest each of the features of independent claims 9 and 19, or the respective claimed combinations of features. Further, as set forth above, Hirobumi fails to overcome the deficiencies of Figures 1-3 of the present application.

Accordingly, it is respectfully submitted that independent claims 9 and 19 are allowable over the applied combination, and thus the rejection of independent claims 9 and 19 under 35 U.S.C. §103(a) over Figures 1-3 of the present application and Hirobumi should be withdrawn. Dependent claims 10-18 are allowable at least for the reasons set forth above with respect to independent claim 9, from which they depend, as well as for their added features.

Likewise, dependent claim 8 is allowable over Figures 1-3 of the present application, either alone or in combination with Hirobumi, at least for the reasons set forth above with respect to independent claim 2, from which it depends, as well as for its added features. Accordingly, the rejection of claim 8 under 35 U.S.C. §103(a) over Figures 1-3 of the present application and Hirobumi should be withdrawn.

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Reply to Office Action of **May 30, 2007**

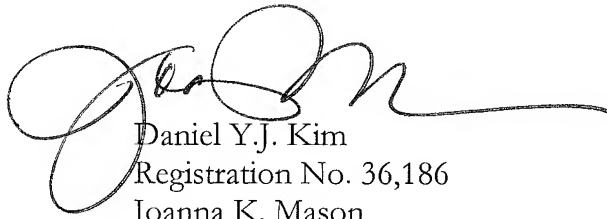
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III. Conclusion

In view of the foregoing amendments and remarks, it is respectfully submitted that the application is in condition for allowance. If the Examiner believes that any additional changes would place the application in better condition for allowance, the Examiner is invited to contact the undersigned **Joanna K. Mason**, at the telephone number listed below.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this, concurrent and future replies, including extension of time fees, to Deposit Account 16-0607 and please credit any excess fees to such deposit account.

Respectfully submitted,
KED & ASSOCIATES, LLP



Daniel Y.J. Kim
Registration No. 36,186
Joanna K. Mason
Registration No. 56,408

P.O. Box 221200
Chantilly, Virginia 20153-1200
703 766-3777 DYK:JKM:lh
Date: October 25, 2007
Q:\Documents\2000-672\136746

Please direct all correspondence to Customer Number 34610